

- 规格书 -

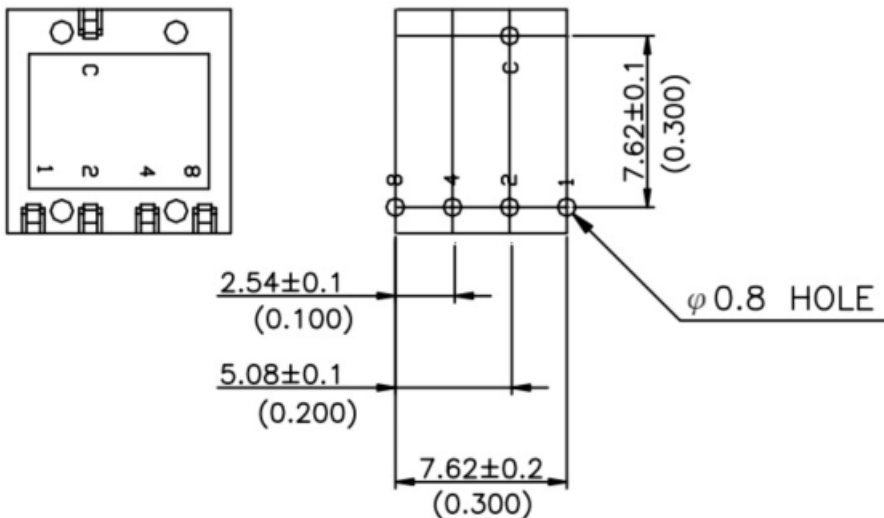
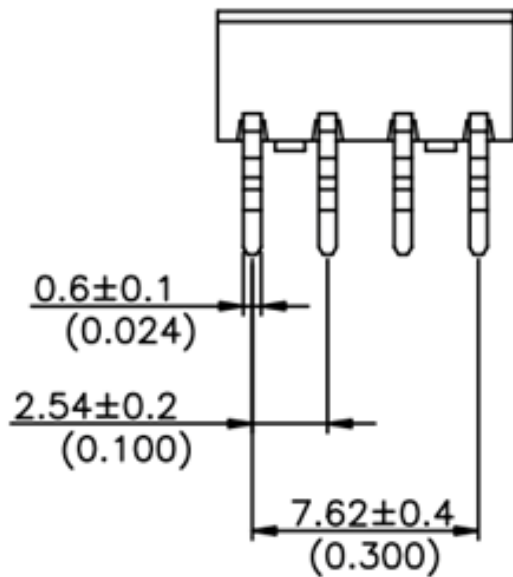
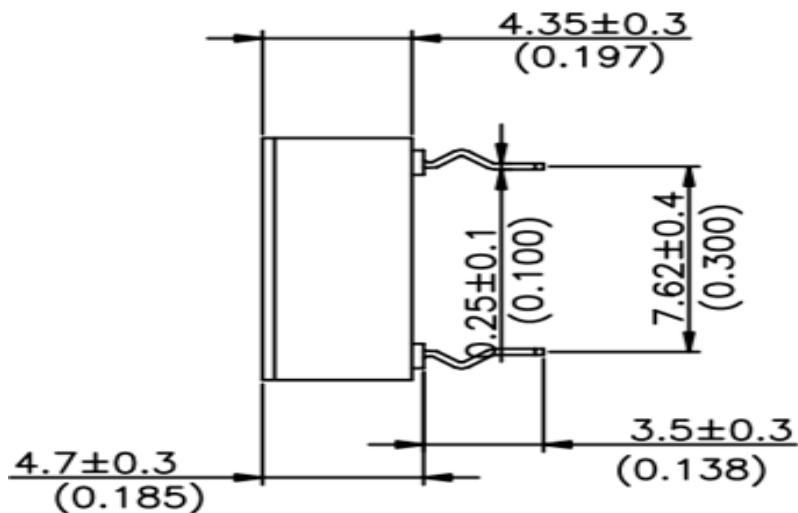
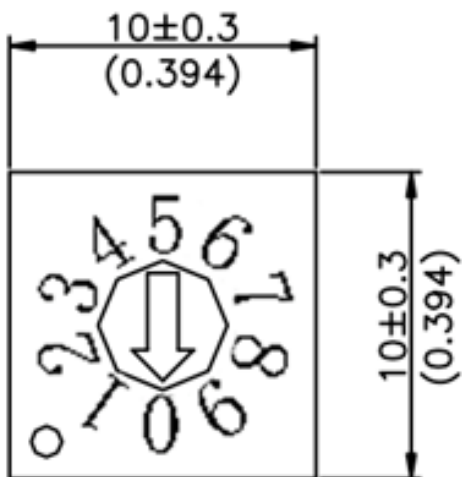
产品型号: BER-10-1YB (thin)

产品名称: 旋转编码开关

SM SWITCH CO.,LTD

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APPD	CHKD	D'SGD	TITLE ROTARY DIP SWITCH				
Y.D WANG	J.S KIM	H.S LEE	MODEL NO.	BER-10-1YB (thin)		REV	A
			SM SWITCH CO., LTD.				

ROTARY DIP SWITCH SPECIFICATION

Rev. B
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1. Style:

This specification describes "Rotary Switch" mainly used as signal switch of electric devices with the general requirements of mechanical and electrical characteristics.

1.1 Operating / Storage Temperature Range : -40℃ ~ +85℃

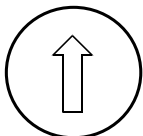
2. Current Range:

2.1 None-Switching : 200 mA, 42V

2.2 Switching : 150 mA, 42V

3. Type of Actuation : Rotating

4. Test Sequence :

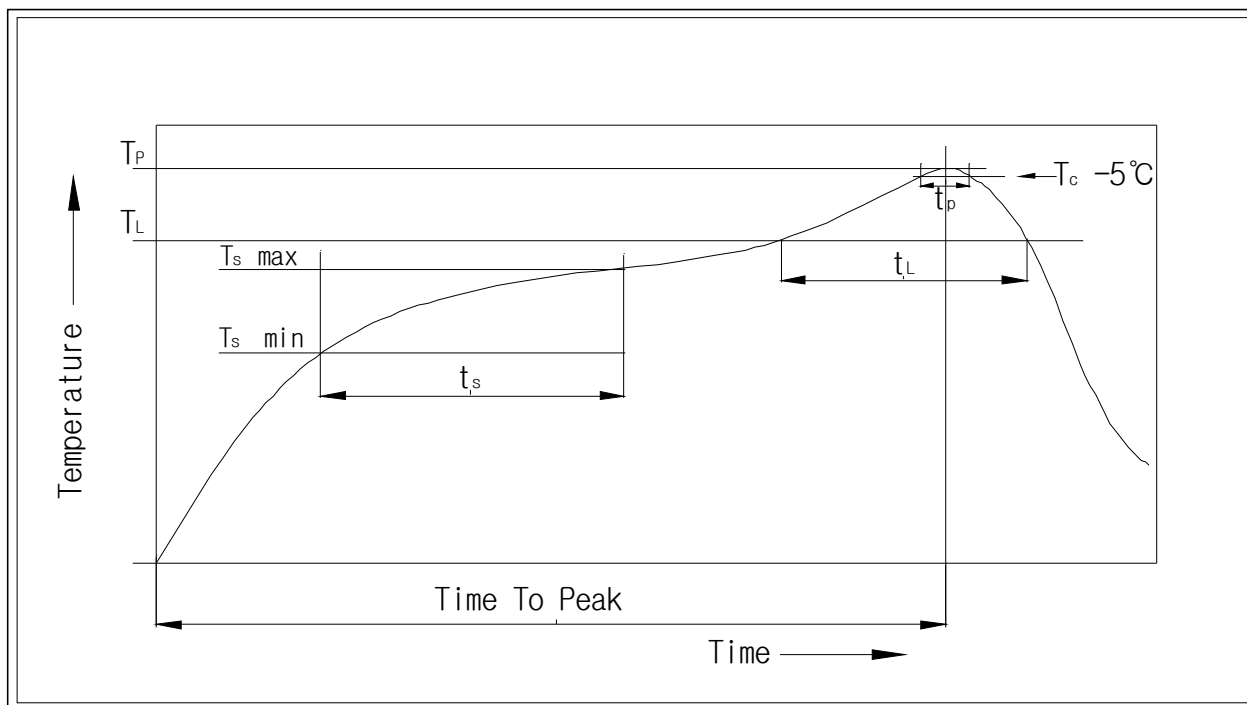
E L E C T R I C P E R F O R M A N C E	ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
	1	Visual Examination	By visual examination check without any out pressure & testing.	There shall be no defects that affect the serviceability of the product
	2	Contact Resistance	① To be measured between the two terminals associated with each switch pole ② Measurements shall be made with a 1kHz shall current contact resistance meter	80mΩ max.(initial)
	3	Insulation Resistance	250V DC, 1minute ±5seconds	100MΩ min
	4	Dielectric withstanding Volotage	250V AC(50Hz or 60Hz)shall be applied between all the adjacent terminal and between the terminal and the frame For 1 minute	There shall be no breakdown or flashover
	5	Operation Force	Applied in the direction of operation 	700gf/cm. max

ROTARY DIP SWITCH SPECIFICATION

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M A C H I N P E R F O R M A N C E	6	Operation Life	Measurements shall be made following the test set forth below: 1)150mA, 42V DC resistive load 2)Rate of operation: 15~20 cycles/ minute 3)Step of operation: 10,000 steps	1)As shown in item 3,4 2)Contact Resistance: 200mΩ max 3)Final-after test
	7	Resistance Low Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: -60℃ ±3℃ 2)Time: 96 hours	1)As shown in item 3~5 2)Contact Resistance: 200mΩ max
	8	Resistance High Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: 125℃ ±2℃ 2)Time: 96 hours	1)As shown in item 3~5 2)Contact Resistance: 200mΩ max
	9	Resistance Humidity	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: 40℃ ±2℃ 2)Relative humidity: 90~95% 3)Time: 96 hours	1)As shown in item 4 2)Contact Resistance: 200mΩ max 3)Insulation Resistance: 10MΩ min

6. Reflow Soldering Conditions:



1) Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Average Ramp-UP Rate($T_s \text{ max}$ to T_P)	$3^\circ\text{C}/\text{second max}$
Preheat - Temperature Min($T_s \text{ min}$) - Temperature Max($T_s \text{ max}$) - Time ($t_s \text{ min}$ to $t_s \text{ max}$)	150°C 200°C 60-100seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	217°C 60-100seconds
Peak/Classification Temperature(T_P)	$240\sim 260^\circ\text{C} \ +0^\circ\text{C}/ \ -5^\circ\text{C}$
Time within 5°C of actual Peak Temperature(t_p)	min 30 seconds
Ramp-Down Rate	$6^\circ\text{C}/\text{sec max}$
Reflow Soldering	$260^\circ\text{C}/4\sim 5 \text{ seconds max}$

7. This item is "ROHS" Compliant

ROTARY DIP SWITCH SPECIFICATION

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8. Part List

NO	PART NAME	Q'TY	MATERIALS	TREATMENT	REMARK
1	COVER	1	PA9T		
2	BASE	1			
3	ACTUATOR	1	PA9T		
4	CONTACT & TERMINAL	1	PHOSPHOR BRONZE	CONTACT AND TERMINAL PLATING: GOLD PLATING OVER NICKEL TINNING	Au 0.03 μ m Min Ni 0.1 μ m Min TIN 0.1 μ m Min
5	PCB	1	EPOXY	PLATING: GOLD PLATING	Au 0.05 μ m Min
6	O-Ring	1	SILICONE		